

	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	2054	(438/612).ccls. or (438/597).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 14:56
2	BRS	337	((438/612).ccls. or (438/597).ccls. and @ad<=20020109) and copper and aluminum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:04
3	BRS	74	((438/612).ccls. or (438/597).ccls. and @ad<=20020109) and 'bonding pad' with 'integrated circuit'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:08
4	BRS	1	((438/612).ccls. or (438/597).ccls. and @ad<=20020109) and Cu adj bonding adj pad with 'integrated circuit'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:13
5	BRS	6	((438/612).ccls. or (438/597).ccls. and @ad<=20020109) and Copper adj bonding adj pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:14
6	BRS	1143	@ad<=20020109 and cu adj 'bonding pad' with 'IMD' or 'intermetal dielectric'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:45
7	BRS	0	@ad<=20020109 and cu adj 'bonding pad' with 'IMD'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:27
8	BRS	0	@ad<=20020109 and cu adj 'bonding pad' with 'intermetal dielectric'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:27
9	BRS	6	@ad<=20020109 and cu adj 'bonding pad' with 'Al'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:28
10	BRS	3	@ad<=20020109 and cu adj 'bonding pad' and 'IMD'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:43
11	BRS	1	"3942245".PN.	USPAT	2002/08/21 11:40
12	BRS	1	"5075965".PN.	USPAT	2002/08/21 11:40
13	BRS	1	"5288006".PN.	USPAT	2002/08/21 11:40
14	BRS	1	"5376235".PN.	USPAT	2002/08/21 11:41
15	BRS	1	"5384284".PN.	USPAT	2002/08/21 11:41
16	BRS	1	"5436412".PN.	USPAT	2002/08/21 11:42
17	BRS	0	@ad<=20020109 and copper adj bonding adj pad with 'intermetal dielectric'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:45
18	BRS	4	@ad<=20020109 and copper adj bonding adj pad and 'intermetal dielectric'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:46
19	IS&R	809	(228/180.21).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:48
20	BRS	93	((228/180.21).CCLS.) and bonding adj pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:50
21	BRS	9	((228/180.21).CCLS.) and bonding adj pad with copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 13:32
22	BRS	8	((228/180.21).CCLS.) and bond adj pad with copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 13:30
23	BRS	0	((228/180.21).CCLS.) and bond adj pad with copper with 'Al' adj buffer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 13:31
24	BRS	0	((228/180.21).CCLS.) and bond adj pad with copper with 'Al'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 13:31

	Type	Hits	Search Text	DBs	Time Stamp
25	BRS	639	@ad<=20010119 and bonding adj pad with copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/21 13:36
26	BRS	359	@ad<=20010119 and bonding adj pad with copper and aluminum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/21 13:47
27	BRS	30	@ad<=20010119 and copper adj bonding adj pad and aluminum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/21 13:59
28	BRS	839	@ad<=20010119 and bonding adj pad and aluminum and buffer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/21 14:00
29	BRS	4120	'bonding pad' and apparatus	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/21 15:03
30	IS&R	3573	((257/459) or (257/676) or (257/786) or (275/670) or (257/672)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/21 15:07